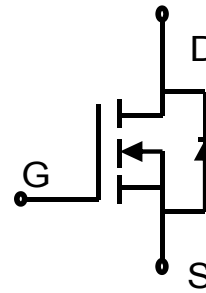




### Description

These N-Channel enhancement mode power field effect transistors are using split gate trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and with stand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.



N-Channel MOSFET

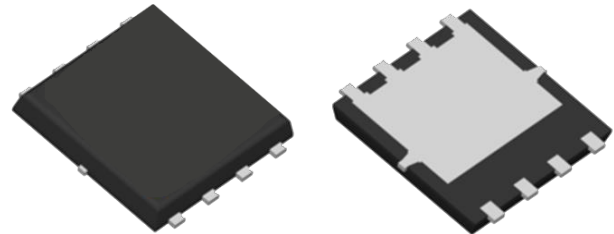
### Features

- ◆ 30V,100A,  $R_{DS(on),max} = 1.6m\Omega @ V_{GS} = 10V$
- ◆ Improved dv/dt capability
- ◆ Fast switching
- ◆ 100% EAS Guaranteed
- ◆ Green device available

### Applications

- ◆ Motor Drives
- ◆ UPS
- ◆ DC-DC Converter

### Pin Configuration



DFN5×6

### Product Summary

$V_{DSS}$	30V
$R_{DS(on),max} @ V_{GS}=10V$	1.6mΩ
$I_D$	100A

### Absolute Maximum Ratings $T_C = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DSS}$	30	V
Continuous drain current ( $T_C = 25^\circ C$ ) <sup>1)</sup> ( $T_C = 100^\circ C$ ) <sup>1)</sup>	$I_D$	100	A
		94	A
Pulsed drain current <sup>2)</sup>	$I_{DM}$	300	A
Gate-Source voltage	$V_{GSS}$	$\pm 20$	V
Avalanche energy <sup>3)</sup>	$E_{AS}$	61	mJ
Power Dissipation	$P_D$	57	W
Storage Temperature Range	$T_{STG}$	-55 to +150	$^\circ C$
Operating Junction Temperature Range	$T_J$	-55 to +150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.2	$^\circ C/W$
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	50	$^\circ C/W$

### Package Marking and Ordering Information

Device	Device Package	Marking	Units/Reel
WLQ016R03	DFN5X6	WLQ016R03	5000



### Electrical Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise noted

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static characteristics</b>						
Drain-source breakdown voltage	$BV_{DSS}$	$V_{GS}=0\text{ V}, I_D=250\mu\text{A}$	30	---	---	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1.2	1.7	2.5	V
Drain-source leakage current	$I_{DSS}$	$V_{DS}=30\text{ V}, V_{GS}=0\text{V}, T_J = 25^\circ\text{C}$	---	---	1	$\mu\text{A}$
Gate leakage current, Forward	$I_{GSSF}$	$V_{GS}=20\text{ V}, V_{DS}=0\text{ V}$	---	---	100	nA
Gate leakage current, Reverse	$I_{GSSR}$	$V_{GS}=-20\text{ V}, V_{DS}=0\text{ V}$	---	---	-100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}, I_D=20\text{ A}$	---	1.32	1.6	mΩ
		$V_{GS}=4.5\text{ V}, I_D=20\text{ A}$	---	1.9	2.5	mΩ
Forward transconductance	$g_{fs}$	$V_{DS}=5\text{V}, I_D=20\text{A}$	---	36.5	---	S
<b>Dynamic characteristics</b>						
Input capacitance	$C_{iss}$	$V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V},$ $F = 1\text{MHz}$	---	3421	---	pF
Output capacitance	$C_{oss}$		---	1914	---	
Reverse transfer capacitance	$C_{riss}$		---	195	---	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15\text{V}, V_{GS}=10\text{V}, I_D = 20\text{A}$ $R_G=3.3\Omega$	---	10.4	---	ns
Rise time	$t_r$		---	6.0	---	
Turn-off delay time	$t_{d(off)}$		---	56.3	---	
Fall time	$t_f$		---	8.1	---	
Gate resistance	$R_g$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}, F=1\text{MHz}$	---	1.1	---	Ω
<b>Gate charge characteristics</b>						
Gate to source charge	$Q_{gs}$	$V_{DS}=15\text{V}, I_D=20\text{A},$ $V_{GS}=10\text{ V}$	---	9.8	---	nC
Gate to drain charge	$Q_{gd}$		---	6.5	---	
Gate charge total	$Q_g$		---	56	---	
<b>Drain-Source diode characteristics and Maximum Ratings</b>						
Continuous Source Current	$I_S$		---	---	47.5	A
Pulsed Source Current <sup>4)</sup>	$I_{SM}$		---	---	142.5	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0\text{V}, I_S=20\text{A}, T_J=25^\circ\text{C}$	---	---	1.2	V

#### Notes:

- 1: The maximum junction current rating is package limited.
- 2: Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3:  $V_{DD}=25\text{V}, V_{GS}=10\text{V}, L=0.1\text{mH}, I_{AS}=35\text{A},$  Starting  $T_J=25^\circ\text{C}$ .
- 4: Pulse Test: Pulse Width  $\leq 300\ \mu\text{s}$ , Duty Cycle  $\leq 2\%$ .



### Electrical Characteristics Diagrams

Figure 1. Typ. Output Characteristics

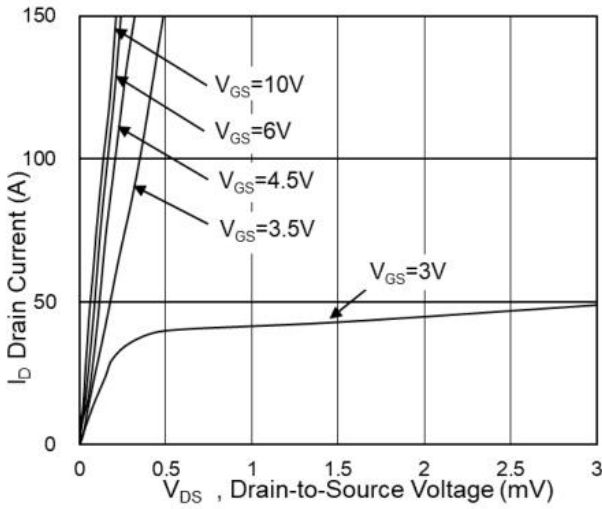


Figure 2. Transfer Characteristics

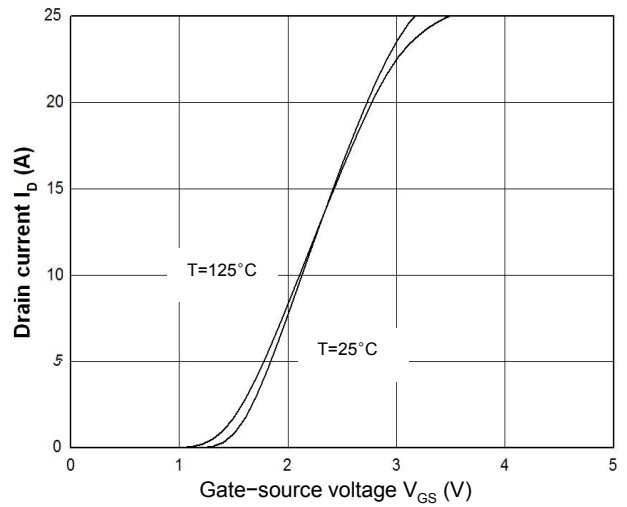


Figure 3. Capacitance Characteristics

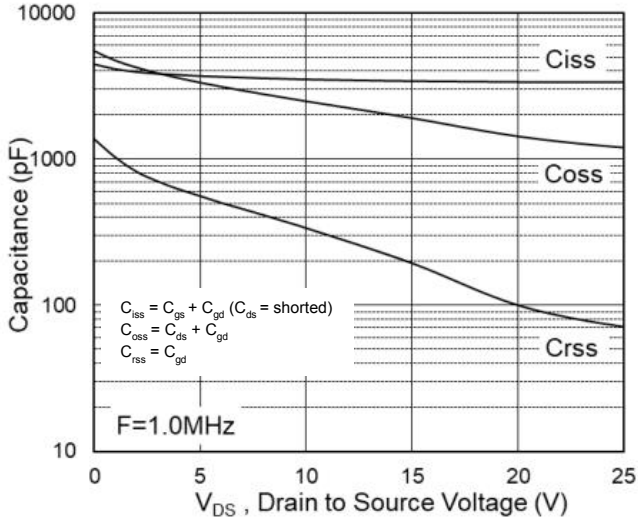


Figure 4. Gate Charge Waveform

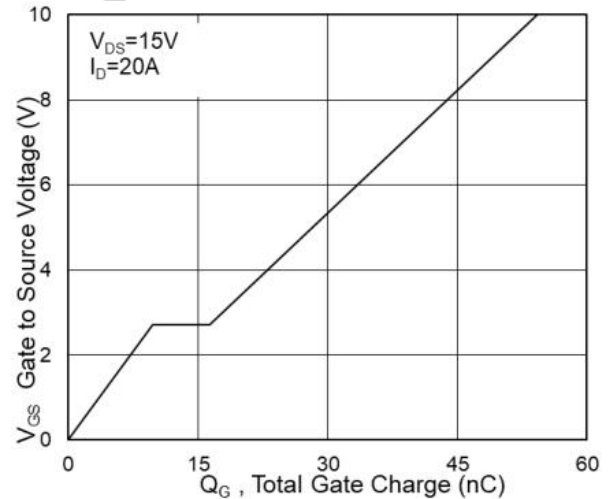


Figure 5. Body-Diode Characteristics

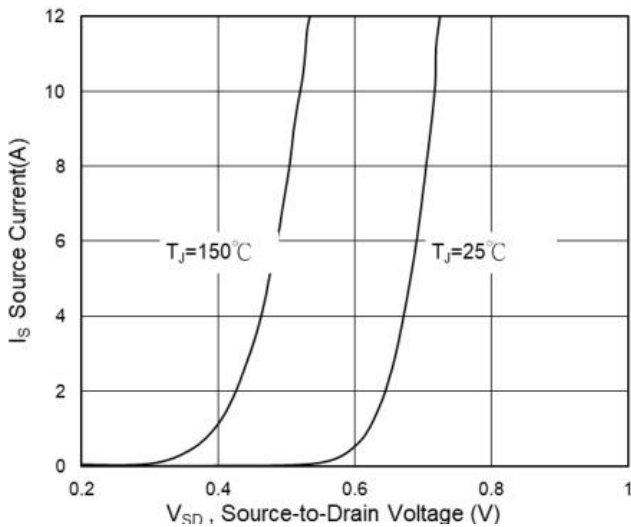


Figure 6. Rdson-Drain Current

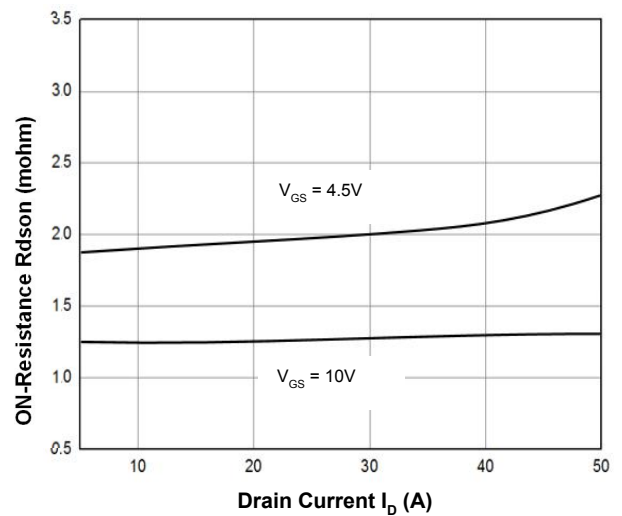




Figure 7. R<sub>ds(on)</sub>-Junction Temperature

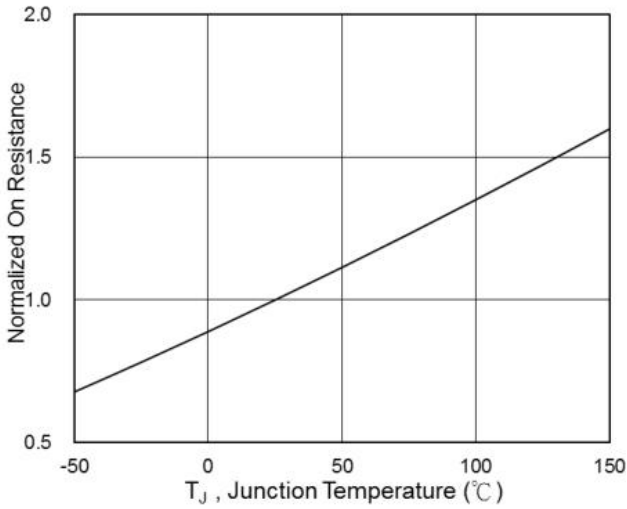


Figure 8. V<sub>GS(th)</sub>-Junction Temperature

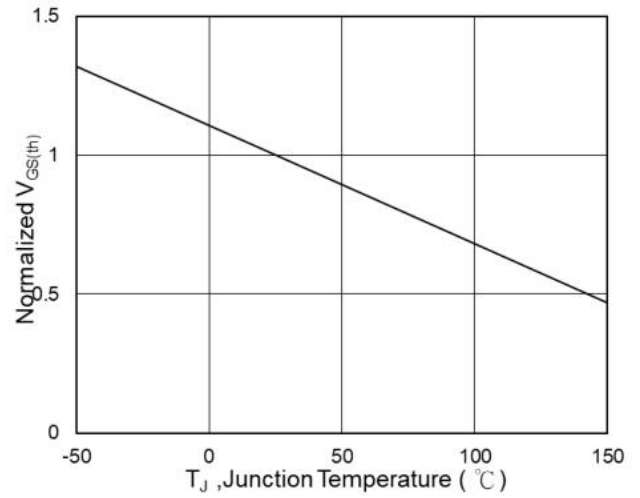


Figure 9. On-Resistance vs. Gate-to-Source voltage

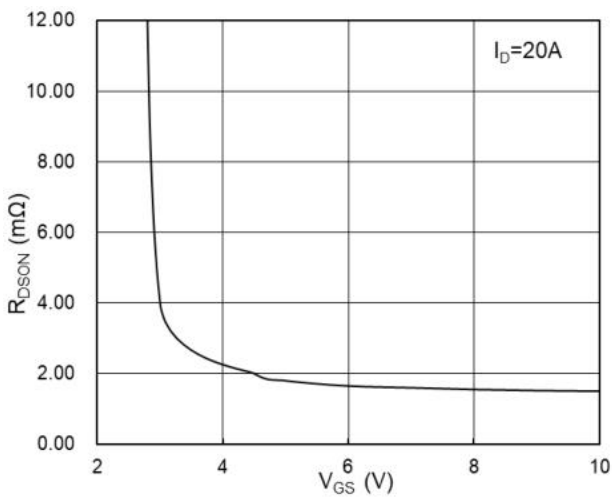


Figure 10: Safe Operating Area

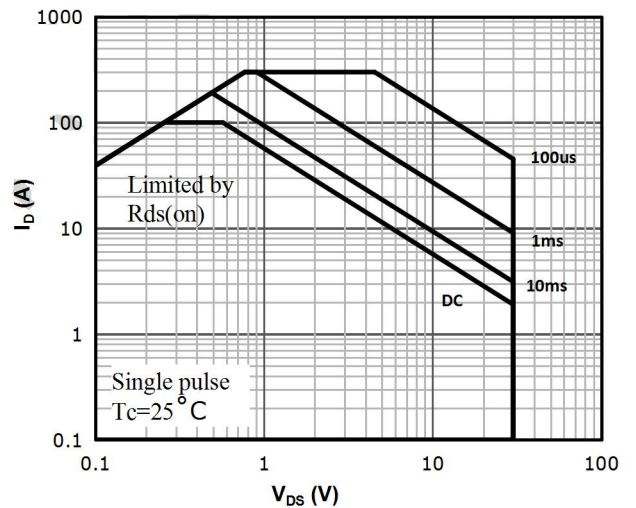
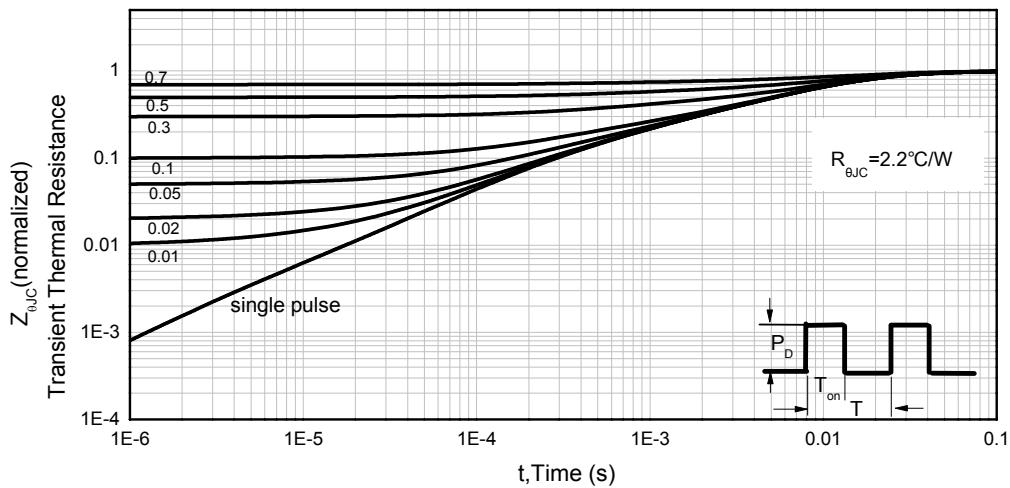


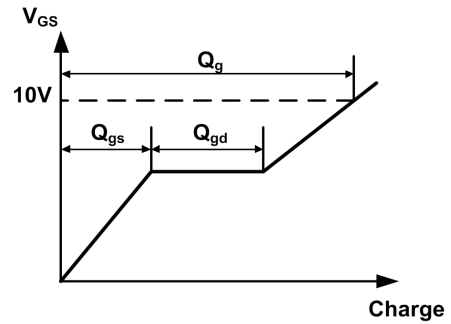
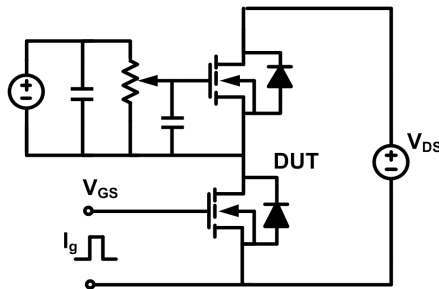
Figure 11. Normalized Maximum Transient Thermal Impedance (R<sub>thJC</sub>)



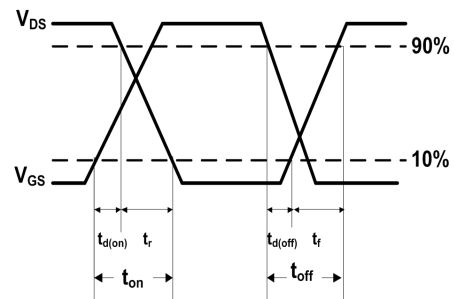
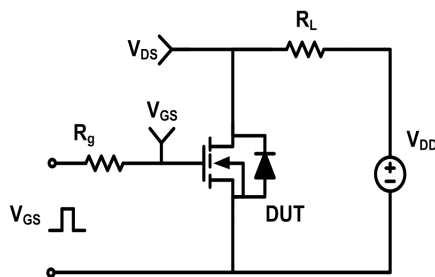


### Test Circuit & Waveforms

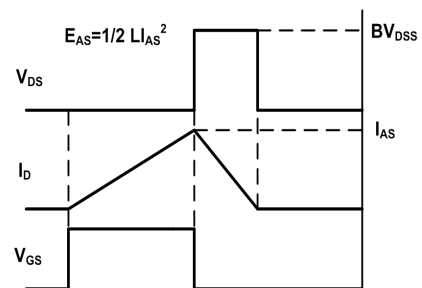
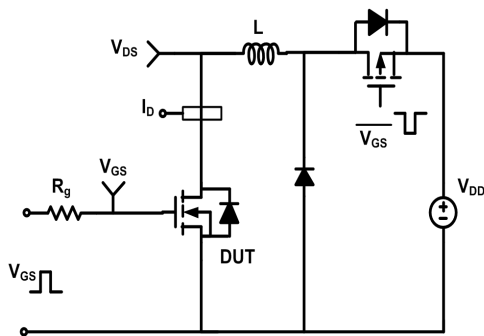
#### Gate Charge Test Circuit & Waveform



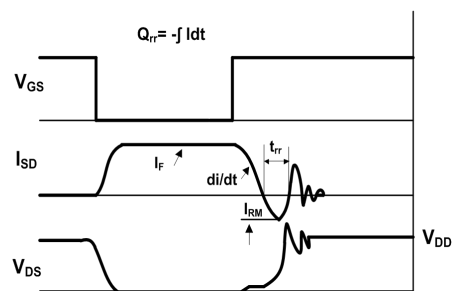
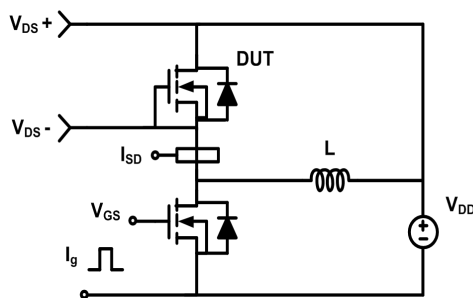
#### Resistive Switching Test Circuit & Waveform



#### Unclamped Inductive Switching (UIS) Test Circuit & Waveform

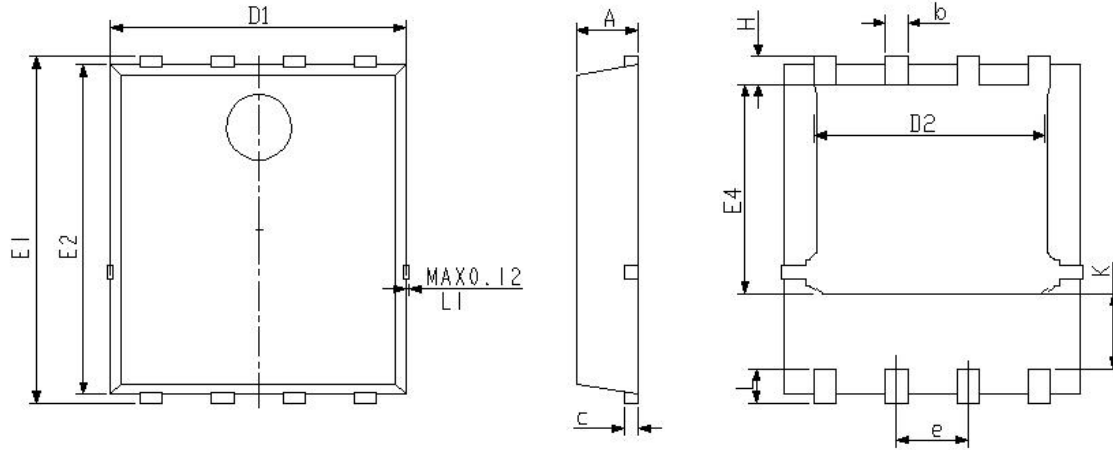


#### Diode Recovery Test Circuit & Waveform





### Mechanical Dimensions for DFN5×6



DIMENSIONS IN MILLIMETERS		
SYMBOL	MIN	MAX
A	0.85	1.20
b	0.30	0.51
c	0.15	0.35
D1	4.80	5.40
D2	3.70	4.55
E1	5.95	6.35
E2	5.45	6.06
E4	3.30	3.92
e	1.27BSC	
L	0.3	0.71
H	0.38	0.71



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